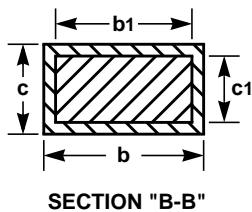
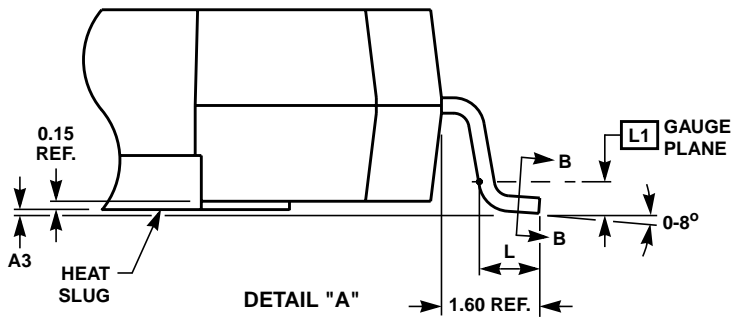
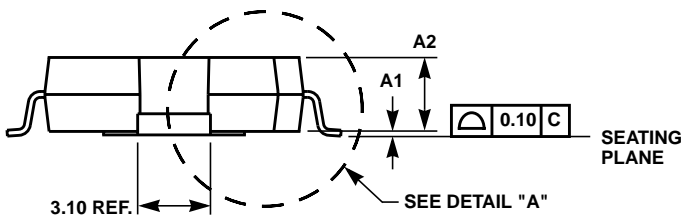
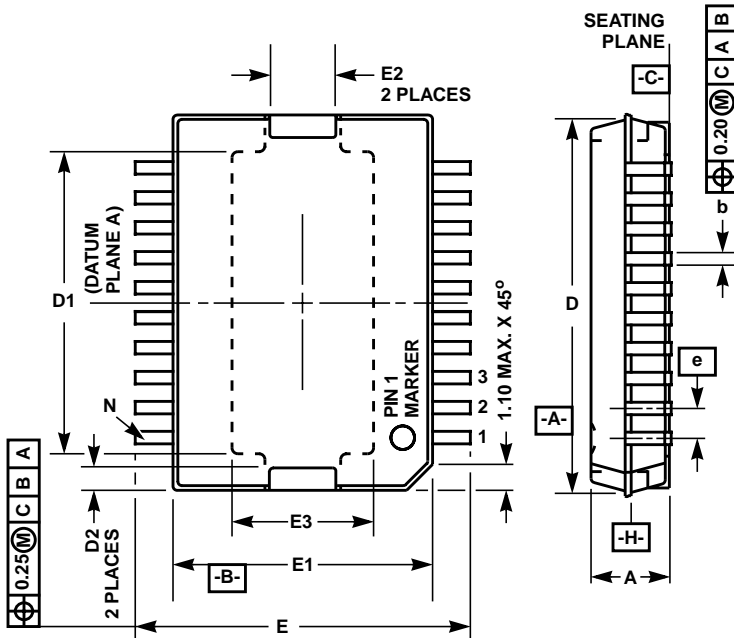


Power Small Outline Plastic Package (PSOP)



M24.433

24 LEAD POWER SMALL OUTLINE PLASTIC PACKAGE

SYM-BOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.122	0.142	3.10	3.60	-
A1	0.004	0.012	0.10	0.30	-
A2	0.118	0.130	3.00	3.30	-
A3	0.000	0.004	0.00	0.10	-
b	0.016	0.021	0.40	0.53	6, 7
b1	0.016	0.020	0.40	0.50	6, 7
c	0.009	0.013	0.23	0.32	7
c1	0.009	0.011	0.23	0.29	7
D	0.622	0.630	15.80	16.00	3
D1	0.496	0.512	12.60	13.00	-
D2	-	0.043	-	1.10	-
E	0.547	0.571	13.90	14.50	-
E1	0.429	0.437	10.90	11.10	4
E2	-	0.114	-	2.90	-
E3	0.228	0.244	5.80	6.20	-
e	0.039 BSC		1.0 BSC		-
L	0.031	0.043	0.80	1.10	5
L1	0.014 BSC		0.35 BSC		-
N	24		24		-

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NOTES:

1. Dimensioning and tolerancing per ANSI Y14.5M-1982.
2. "C" is a reference datum. Seating plane is defined by lead tips only.
3. Dimension D does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15 per side. D measured at -H-.
4. Dimension E1 does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.15 per side. E1 measured at -H-.
5. Dimension "L" is the length of terminal for soldering to a substrate.
6. The lead width dimension does not include dambar protrusion. Allowable dambar protrusion shall be 0.08mm total in excess of the lead width dimension at maximum material condition.
7. Section "B-B" to be determined at 0.10mm to 0.25mm from the lead tip.
8. Controlling dimension: MILLIMETER.
9. Dimensions conform with JEDEC Outline MO-166AC Issue C.

